



Material Content Data Sheet



Sales Product Name	IFX52001EJ			Issued		29. August 2013		
MA#	MA001094964							
Package	PG-DSO-8-27			Weight*		84.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.187	3.77	3.77	37730	37730
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.728	0.86		8614	
	non noble metal	copper	7440-50-8	29.548	34.98	35.89	349755	358908
wire	noble metal	gold	7440-57-5	0.066	0.08	0.08	782	782
encapsulation	organic material	carbon black	1333-86-4	0.096	0.11		1135	
	plastics	epoxy resin	-	4.410	5.22		52198	
	inorganic material	silicondioxide	60676-86-0	43.426	51.41	56.74	514036	567369
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8228	8228
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8576	8576
glue	plastics	epoxy resin	-	0.389	0.46		4602	
	noble metal	silver	7440-22-4	1.166	1.38	1.84	13805	18407
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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